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**AMENDMENT 3**  
2018-04

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**Identification cards — Test  
methods —**

**Part 6:  
Proximity cards**

**AMENDMENT 3: PICC loading effect**

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*Cartes d'identification — Méthodes d'essai —*  
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*Partie 6: Cartes de proximité*

**AMENDEMENT 3: Effet de charge PICC**  
**ISO/IEC 10373-6:2016/Amd 3:2018**

<https://standards.iteh.ai/catalog/standards/sist/3bfad67b-665c-42e5-ac67-c7f7dd3cbadc/iso-iec-10373-6-2016-amd-3-2018>



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## Foreword

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The procedures used to develop this document and those intended for its further maintenance are described in the ISO/IEC Directives, Part 1. In particular the different approval criteria needed for the different types of document should be noted. This document was drafted in accordance with the editorial rules of the ISO/IEC Directives, Part 2 (see [www.iso.org/directives](http://www.iso.org/directives)).

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The document was prepared by ISO/IEC JTC 1, *Information technology, SC 17, Cards and security devices for personal identification*.

A list of all the parts in the ISO 10373 series can be found on the ISO website.

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## Identification cards — Test methods —

### Part 6: Proximity cards

#### AMENDMENT 3: PICC loading effect

Page 18, 7.1

Replace Table 3 and NOTE with the following Table 3 and sentence:

**Table 3 — Class parameters**

Class	Reference PICC	$V_{load}$	$R2_{min}$	$R2_{max}$	Test PCD assembly
1	1	4,5 V	647 $\Omega$	791 $\Omega$	Test PCD assembly 1
2	2	4,5 V	1 030 $\Omega$	1 260 $\Omega$	Test PCD assembly 1
3	3	4,5 V	1 080 $\Omega$	1 320 $\Omega$	Test PCD assembly 1
4	4	4,5 V	990 $\Omega$	1 210 $\Omega$	Test PCD assembly 2
5	5	4,5 V	960 $\Omega$	1 170 $\Omega$	Test PCD assembly 2
6	6	4,5 V	700 $\Omega$	900 $\Omega$	Test PCD assembly 2

The PCD should be tested with a  $V_{load}$  of 6 V for Reference PICC 1 to ensure interoperability with PICCs compliant with the  $V_{load}$  requirement of ISO/IEC 10373-6:2016.

Page 19, 7.1.1.2.2

After step c) add:

- d) For Reference PICC 1 repeat:
- 1) step b) with a DC voltage  $V_{load}$  of 6 V measured at connector CON3 instead of  $V_{load}$  as defined in Table 3, and
  - 2) step c), where the DC voltage at CON3 shall exceed 5,3 V [corresponding to  $H_{min} - 0,2$  A/m(rms)], instead of  $V_{load}$  as defined in Table 3.

Page 19, 7.1.1.3

Replace the whole paragraph with:

“The test report shall confirm the operating volume in which the DC voltage measured at CON3 for R2 or variable load resistor adjusted to  $H_{min}$  and  $H_{max}$  field strength fulfils the requirements defined in step d) of 7.1.1.2.1 and in step c) of 7.1.1.2.2.”

After step f) add:

If PICC “Class 1” parameters were used and if the field strength measured in step f) was not greater than  $H_{\min}$ , then the following alternative procedure may be used to measure the PICC loading effect:

— repeat steps b) to f) using Reference PICC 1 configured for a  $V_{\text{load}}$  of 6 V instead of the voltage defined in Table 3;

NOTE 1 The warning about R2 value is not applicable in this case.

— repeat the PICC transmission test defined in 7.2.1 with a field strength of  $H_{\min} - 0,2 \text{ A/m(rms)}$  instead of  $H_{\min}$ , as defined in ISO/IEC 14443-2:2016, Table 2, using the  $V_{\text{LMA, PICC}}$  limit defined for  $H_{\min}$ , as defined in ISO/IEC 14443-2:2016, Table 8;

— repeat the PICC EMD level and low EMD time test defined in 7.2.2 with a field strength of  $H_{\min} - 0,2 \text{ A/m(rms)}$  instead of  $H_{\min}$ , as defined in ISO/IEC 14443-2:2016, Table 2, using the  $V_{\text{E, PICC}}$  limit defined for  $H_{\min}$ , as defined in ISO/IEC 14443-2:2016, 10.2;

— repeat the PICC reception test defined in 7.2.3 with a field strength of  $H_{\min} - 0,2 \text{ A/m(rms)}$  instead of  $H_{\min}$ , as defined in ISO/IEC 14443-2:2016, Table 2, using, for Type B PICC, the modulation index,  $m$ , defined for  $H_{\min}$ , as defined in ISO/IEC 14443-2:2016, 9.1.2.1.

NOTE 2 This alternative procedure checks that a slightly higher PICC loading effect is compensated by a slightly lower PICC minimum operating field strength.

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Replace the whole subclause with: [ISO/IEC 10373-6:2016/Amd 3:2018](https://standards.iteh.ai/catalog/standards/sist/3bfad67b-665c-42e5-ac67-c717ad5c0acc/iso-iec-10373-6-2016-amd-3-2018)

If the alternative procedure has not been used, the test result is only PASS if the field strength measured in step f) is greater than  $H_{\min}$ , otherwise the test result is FAIL.

If the alternative procedure has been used, the test result is only PASS if the field strength measured in step f) is greater than  $H_{\min}$  (using Reference PICC 1 configured for a DC voltage  $V_{\text{load}}$  of 6 V) and if the PICC transmission test defined in 7.2.1, the PICC EMD level and low EMD time test defined in 7.2.2 and the PICC reception test defined in 7.2.3 are PASS with a field strength of  $H_{\min} - 0,2 \text{ A/m(rms)}$  instead of  $H_{\min}$ , otherwise the test result is FAIL.

The test report shall give the value of the measured field strength and the  $V_{\text{load}}$  value used.

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